

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Masaru SHIRAI et al.                      Group Art Unit : 1725  
Appl. No. : 10/598,142                                      Examiner :  
Filed : August 18, 2006                                      Confirmation No. : 1550  
For : HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING  
METHOD AND APPARATUS

**RESPONSE TO REQUIREMENT FOR RESTRICTION**

Commissioner for Patents  
U.S. Patent and Trademark Office  
Customer Service Window, Mail Stop AMENDMENT  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir :

This paper responds to the Requirement for Restriction under 35 U.S.C. § 121 and 35 U.S.C. § 372 mailed from the U.S. Patent and Trademark Office on February 9, 2009. Inasmuch as the Office Action sets a one-month shortened statutory period for response, to end March 9, 2009, no fee is believed due at this time. However, the Office is authorized to charge any required fee to Deposit Account No. 19-0089.

**Remarks**, including an election without traverse, begin on page 2 of this paper.